

HY2510BF-H2B Data Sheet

1-Cell Lithium-ion/Lithium Polymer Battery Packs Protection IC



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1. General Description

The HY2510BF-H2B is a protection IC for single-cell lithium-ion/lithium polymer rechargeable battery and it also comprises high-accuracy voltage detectors and delay circuits. The IC is applicable to protect single-cell rechargeable lithium-ion/lithium polymer battery packs from overcharge, overdischarge and overcurrent.

2. Features

(1) High-accuracy voltage detection circuit

Overcharge detection voltage	4.425V	Accuracy: ±20mV
Overcharge release voltage	4.225V	Accuracy: ±30mV
Overdischarge detection voltage	2.800 V	Accuracy: ±50mV
Overdischarge release voltage	3.000V	Accuracy: ±50mV
Discharge overcurrent detection voltage	130mV	Accuracy: ±10mV
Charge overcurrent detection voltage	-100mV	Accuracy: ±5mV
Short-circuiting detection voltage	400mV	Accuracy: ±40mV

(2) Low current consumption

Operation mode 3.0µA typ., 6.0µA max. (VDD=3.9V)
 Overdischarge Current Consumption 0.16µA typ., 0.5µA max. (VDD=2.0V)

(3) Delay times are generated by an internal circuit (external capacitors are unnecessary).

Overcharge delay time
 Overdischarge delay time
 Discharge overcurrent delay time
 Charge overcurrent delay time
 Short-circuit delay time
 350µs typ.

(4) With Auto over discharge recovery

(5) 0 V battery charge function: "Available"

(6) High-withstanding-voltage: CS pin and OC pin: Absolute maximum rating = 20 V.

(7) Wide operation temperature range: -40°C to +85 °C

(8) Package: SON-1.6 *1.6-6L

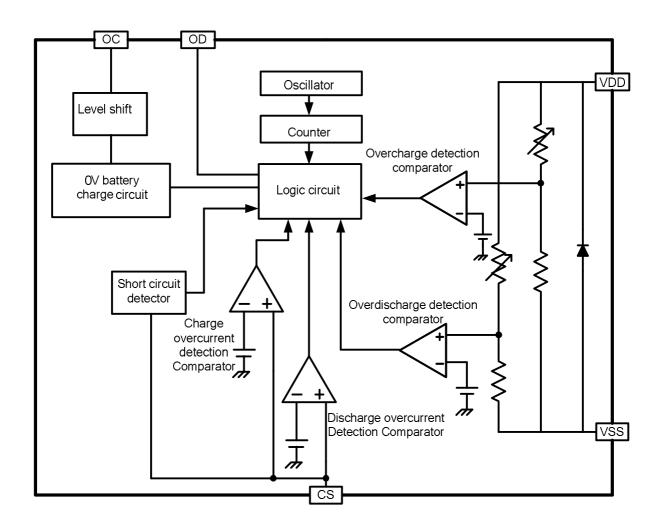
(9) Halogen-free, green package

3. Applications

- 1-cell lithium-ion rechargeable battery packs
- 1-cell lithium polymer rechargeable battery packs

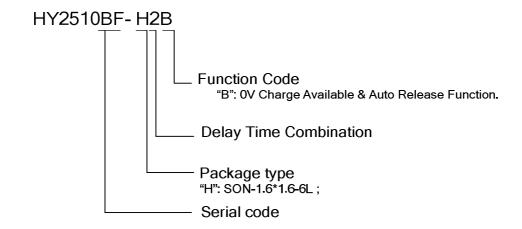


4. Block Diagram





5. Ordering Information



6. Pin Configuration and Package Marking Information

Table 1 SON-1.6*1.6-6L

Pin No.	Symbol	Description
1	NC	No connection.
2	ОС	MOSFET gate connection pin for charge control
3	OD	MOSFET gate connection pin for discharge control
4	VSS	Ground pin
5	VDD	Power supply pin
6	CS	Input pin for current sense, charger detect pin



H: Product name code.

BF: Serial code.

B: Function code.

XXX: Traceability code.

7. Absolute Maximum Ratings

Table 2 Absolute Maximum Ratings (VSS=0V, Ta=25°C unless otherwise specified)

Item	Symbol	Rating	Unit
Input voltage between VDD and VSS pin	V_{DD}	VSS-0.3 to VSS+9	V
OC output pin voltage	V _{oc}	VDD-20 to VDD+0.3	V
OD output pin voltage	V _{OD}	VSS-0.3 to VDD+0.3	V
CS input pin voltage	V _{CS}	VDD-20 to VDD+0.3	V
Operating Temperature Range	T _{OP}	-40 to +85	°C
Storage Temperature Range	T _{ST}	-40 to +125	°C
Power dissipation	P _D	250	mW



8. Electrical Characteristics

Table 3 Electrical Characteristics (VSS=0V, Ta=25°C unless otherwise specified)

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
	-	SUPPLY POWER RANGE				
Operating voltage between VDD pin and VSS pin	V _{DSOP1}	-	1.5	-	6.0	V
Operating voltage between VDD pin and CS pin	V_{DSOP2}	-	1.5	-	20	V
		INPUT CURRENT				
Supply Current	I _{DD}	V _{DD} =3.9V	-	3.0	6.0	μA
Overdischarge Current Consumption	I _{OD}	V _{DD} =2.0V	-	0.16	0.5	μA
·	l	DETECTION VOLTAGE	•	•	l.	•
Overcharge Detection Voltage	V _{CU}		4.405	4.425	4.445	V
Overcharge Release Voltage	V_{CR}		4.195	4.225	4.255	V
Overdischarge Detection Voltage	V_{DL}		2.750	2.800	2.850	V
Overdischarge Release Voltage	V_{DR}		2.950	3.000	3.050	V
Discharge Overcurrent Detection Voltage	V_{DIP}	V _{DD} =3.6V	120	130	140	mV
Charge Overcurrent Detection Voltage	V _{CIP}	V _{DD} =3.6V	-105	-100	-95	mV
Short Circuit Detection Voltage	V _{SIP}	V _{DD} =3.0V	360	400	440	mV
-	•	DELAY TIME				
Overcharge Delay Time	Toc	V _{DD} =4.0V→4.6V	800	1000	1200	ms
Overcharge Release Delay Time	T _{OCR}	V _{DD} =4.6V→4.0V	12.8	16.0	19.2	ms
Overdischarge Delay Time	T _{OD}	V _{DD} =3.2V→2.0V	16	20	24	ms
Overdischarge Release Delay Time	T _{ODR}	V _{DD} =2.0V→3.2V	0.7	1.0	1.3	ms
Discharge Overcurrent Delay Time	T_DIP	V _{DD} =3.6V, CS=0.0V→V _{DIP}	3.2	4.0	4.8	ms
Discharge Overcurrent Release Delay Time	T _{DIPR}	V _{DD} =3.6V, CS=V _{DIP} →0V	9.6	12.0	14.4	ms
Charge Overcurrent Delay Time	T _{CIP}	V _{DD} =3.6V, CS=0.0V→V _{CIP}	3.2	4.0	4.8	ms
Charge Overcurrent Release Delay Time	T _{CIPR}	V _{DD} =3.6V, CS=V _{CIP} →0.0V	6.4	8.0	9.6	ms
Short Circuit Delay Time	T _{SIP}	V _{DD} =3.2V, CS=0.0V→0.6V	200	350	500	μs
•		NTROL OUTPUT VOLTAGE(C	DD&OC)			
OD Pin Output "H" Voltage	V_{DH}		VDD-0.1	VDD-0.02	-	V
OD Pin Output "L" Voltage	V_{DL}		-	0.1	0.5	V
OC Pin Output "H" Voltage	V _{CH}		VDD-0.1	VDD-0.02	-	V
OC Pin Output "L" Voltage	V _{CL}	TERV OUADOE EUNOTION		0.1	0.5	V
OV bottom, oborga starting	UV BAT	TERY CHARGE FUNCTION(A	AVAILABLE)			
0V battery charge starting charger voltage	V_{0ch}	0V battery charge function "Available"	0.0	0.7	1.2	V

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Tale 4 Electrical Characteristics (VSS=0V, Ta=-20°C ~60°C (NOTE))

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
		SUPPLY POWER RANG	E	7.		1
Operating voltage between VDD pin and VSS pin	V _{DSOP1}	-	1.5	-	6.0	V
Operating voltage between VDD pin and CS pin	V_{DSOP2}	-	1.5	-	20	V
		INPUT CURRENT				
Supply Current	I_{DD}	V _{DD} =3.9V	-	3.0	6.0	μA
Overdischarge Current Consumption	I _{OD}	V _{DD} =2.0V	-	0.16	0.5	μA
		DETECTION VOLTAGE				•
Overcharge Detection Voltage	V _{CU}		4.400	4.425	4.450	V
Overcharge Release Voltage	V_{CR}		4.190	4.225	4.260	V
Overdischarge Detection Voltage	V_{DL}		2.745	2.800	2.855	V
Overdischarge Release Voltage	V_{DR}		2.945	3.000	3.055	V
Discharge Overcurrent Detection Voltage	V_{DIP}	V _{DD} =3.6V	115	130	145	mV
Charge Overcurrent Detection Vvoltage	V _{CIP}	V _{DD} =3.6V	-115	-100	-85	mV
Short Circuit Detection Voltage	V _{SIP}	V _{DD} =3.0V	340	400	460	mV
		DELAY TIME				
Overcharge Delay Time	T _{OC}	V _{DD} =4.0V→4.6V	700	1000	1350	ms
Overcharge Release Delay Time	T _{OCR}	V _{DD} =4.6V→4.0V	11.2	16.0	21.6	ms
Overdischarge Delay Time	T _{OD}	V _{DD} =3.2V→2.0V	14	20	27	ms
Overdischarge Release Delay Time	T_{ODR}	V _{DD} =2.0V→3.2V	0.5	1.0	1.5	ms
Discharge Overcurrent Delay Time	T _{DIP}	V _{DD} =3.6V, CS=0.0V→V _{DIP}	8.4	12.0	16.2	ms
Discharge Overcurrent Release Delay Time	T_{DIPR}	V_{DD} =3.6V, CS= V_{DIP} \rightarrow 0V	2.8	4.0	5.4	ms
Charge Overcurrent Delay Time	T _{CIP}	V _{DD} =3.6V, CS=0.0V→-0.1V	5.6	8.0	10.8	ms
Charge Overcurrent Release Delay Time	T _{CIPR}	V_{DD} =3.6V, CS= V_{CIP} \rightarrow 0.0V	2.8	4.0	5.4	ms
Short Circuit Delay Time	T _{SIP}	V _{DD} =3.2V, CS=0.0V→0.6V	150	350	550	μs
·		NTROL OUTPUT VOLTAGE(OD&OC)			
OD Pin Output "H" Voltage	V_{DH}		VDD-0.1	VDD-0.02	-	V
OD Pin Output "L" Voltage	V_{DL}		-	0.1	0.5	V
OC Pin Output "H" Voltage	V _{CH}		VDD-0.1	VDD-0.02	-	V
OC Pin Output "L" Voltage	V _{CL}		-	0.1	0.5	V
OV hadra also to the	OV BA	TTERY CHARGE FUNCTION(AVAILABLE)			1
0V battery charge starting charger voltage	V _{0ch}	0V battery charge function "Available"	0.0	0.7	1.2	V

Note: Since products are not screened at high and low temperature, the specification for this temperature range is guaranteed by design, not tested in production.



Tale 5 Electrical Characteristics (VSS=0V, Ta=-40°C ~85°C (NOTE))

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
		SUPPLY POWER RANG	GE			
Operating voltage between VDD pin and VSS pin	V _{DSOP1}		1.5	-	6.0	V
Operating voltage between VDD pin and CS pin	V _{DSOP2}		1.5	-	20	V
		INPUT CURRENT		<u> </u>		
Supply Current	I _{DD}	V _{DD} =3.9V	-	3.0	6.0	μA
Overdischarge Current Consumption	I _{OD}	V _{DD} =2.0V	-	0.16	0.5	μA
		DETECTION VOLTAG	E			
Overcharge Detection Voltage	V _{CU}		4.390	4.425	4.460	V
Overcharge Release Voltage	V _{CR}		4.180	4.225	4.270	V
Overdischarge Detection Voltage	V_{DL}		2.735	2.800	2.865	V
Overdischarge Release Voltage	V_{DR}		2.935	3.000	3.065	V
Discharge Overcurrent Detection Voltage	V_{DIP}	V _{DD} =3.6V	115	130	145	mV
Charge Overcurrent Detection Voltage	V _{CIP}	V _{DD} =3.6V	-115	-100	-85	mV
Short Circuit Detection Voltage	V _{SIP}	V _{DD} =3.0V	340	400	460	mV
	1	DELAY TIME				1
Overcharge Delay Time	Toc	V _{DD} =4.0V→4.6V	600	1000	1600	ms
Overcharge Release Delay Time	T _{OCR}	V _{DD} =3.6V→4.6V	9.6	16.0	25.6	ms
Overdischarge Delay Time	T _{OD}	V _{DD} =3.2V→2.0V	12	20	32	ms
Overdischarge Release Delay Time	T _{ODR}	V _{DD} =2.0V→3.2V	0.4	1.0	1.6	ms
Discharge Overcurrent Delay Time	T _{DIP}	V_{DD} =3.6V, CS=0.0V \rightarrow V _{DIP}	7.2	12.0	19.2	ms
Discharge Overcurrent Release Delay Time	T _{DIPR}	V_{DD} =3.6V, CS= V_{DIP} \rightarrow 0V	2.4	4.0	6.4	ms
Charge Overcurrent Delay Time	T _{CIP}	V _{DD} =3.6V, CS=0.0V→-0.1V	4.8	8.0	12.8	ms
Charge Overcurrent Release Delay Time	T _{CIPR}	V_{DD} =3.6V, CS= V_{CIP} \rightarrow 0.0V	2.4	4.0	6.4	ms
Short Circuit Delay Time	T _{SIP}	V _{DD} =3.2V, CS=0.0V→0.6V	100	350	600	μs
		CONTROL OUTPUT VOLTAGE				1 10.0
OD Pin Output "H" Voltage	V_{DH}		VDD-0.1	VDD-0.02		V
OD Pin Output "L" Voltage	V_{DL}		-	0.1	0.5	V
OC Pin Output "H" Voltage	V_{CH}		VDD-0.1	VDD-0.02	-	V
OC Pin Output "L" Voltage	V _{CL}		-	0.1	0.5	V
	0V E	BATTERY CHARGE FUNCTION	I(AVAILABLE)		1
0V battery charge starting charger voltage	V _{0ch}	0V battery charge function "Available"	0.0	0.7	1.2	V

Note: Since products are not screened at high and low temperature, the specification for this temperature range is guaranteed by design, not tested in production.

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9. Test condition and circuit

9.1. Test condition

9.1.1 **Supply Current** (Test circuit 1)

Apply 3.9V to V1 with SW=ON (Normal mode). The VDD terminal current in this state is Supply Current (I_{DD}).

9.1.2 **Overdischarge Current Consumption** (Test circuit 1)

Apply 2.0V to V1 with SW=OFF (Overdischarge mode). The VDD terminal current in this state is current consumption (I_{OD}).

9.1.3 Overcharge Detection Voltage, Overcharge Release Voltage (Test circuit 2)

Apply V1=3.6V with V2=0V, increase V1 voltage gradually from normal mode. **Overcharge Detection Voltage** (V_{CU}) is the V1 voltage when V_{OC} turns to "L" level from "H" level. Setting V2=0V, **Overcharge Release Voltage** (V_{CR}) is defined as the voltage V1 at which V_{OC} turns to "H" level from "L" level when the voltage V1 is gradually decreased.

9.1.4 Overdischarge Detection Voltage, Overdischarge Release Voltage (Test circuit 2) Apply V2=0V, and V1 is gradually decreased from normal mode. Overdischarge Detection Voltage (V_{DL}) is the voltage V1 when V_{OD} turns to "L" .level from "H" level.
Overdischarge Release Voltage (V_{DR}) is defined as the voltage V1 at which V_{OD} turns to "H"

from "L" level when the voltage V1 is gradually increased.

9.1.5 **Discharge Overcurrent Detection Voltage** (Test circuit 2)

Apply 3.6V to V1, 0V to V2 and increase V2 voltage gradually from normal mode. **Discharge**Overcurrent Detection Voltage (V_{DIP}) is the V2 voltage when V_{OD} turns "L" level from "H" level.

9.1.6 Charge Overcurrent Detection Voltage (Test circuit 2)

Apply 3.6V to V1, 0V to V2 and decrease V2 voltage gradually from Normal mode. **Charge Overcurrent Detection Voltage** (V_{CIP}) is the V2 voltage when V_{OC} turns to "L" level from "H" level.

9.1.7 **Short Circuit Detection Voltage** (Test circuit 2)

Apply 3.0V to V1, 0V to V2 and increase V2 voltage gradually from normal mode. **Short Circuit Detection Voltage (V_{SIP})** is defined as the voltage V2 whose delay time for changing V_{OD} from "H" to "L" in Short Circuit Detection Delay Time (T_{SIP}).

9.1.8 Overcharge detection delay time, Overcharge release delay time (Test circuit 3)

Apply 0V to V2, and increase V1 from 4.0V (Normal mode) to 4.6V. Overcharge Detection Delay Time (T_{OC}) is the time from V1 exceeds **Overcharge Detection Voltage** until V_{OC} turns to "L".

Apply 0V to V2, and decrease V1 from 4.6V (Overcharge mode) to 4.0V. **Overcharge Release Delay Time (T_{OCR})** is the time form V1 falls below Overcharge Release Voltage until V_{OC} turns "H" level.

9.1.9 Overdischarge Detection Delay Time, Overdischarge Release Delay Time (Test circuit 3)

Apply 0V to V2, and decrease V1 from 3.6V (Normal mode) to 2.0V. Overdischarge



Detection Delay Time (T_{OD}) is the time from V1 falls below Overdischarge Detection Voltage until V_{OD} turns to "L".

Apply 0V to V2, and increase V1 from 2.0V (Overdischarge mode) to 3.6V. **Overdischarge Release Delay Time** (T_{ODR}) is the time from V1 exceeds Overdischarge Release Voltage until V_{OD} turns to "H".

9.1.10 Discharge Overcurrent Delay Time, Discharge Overcurrent Release Delay Time (Test circuit 3)

Apply 3.6V to V1, and increase V2 from 0V (Normal mode) to **Discharge Overcurrent Detection Voltage** (V_{DIP}). Discharge Overcurrent Delay Time (T_{DIP}) is the time from V2 exceeds Discharge Overcurrent Detection Voltage until V_{OD} turns to "L".

Apply 3.6V to V1, and decrease V2 from **Discharge Overcurrent Detection Voltage** (V_{DIP}) to 0V. Discharge Overcurrent Release Delay Time (T_{DIPR}) is the time from V2 falls below Discharge Overcurrent Release Voltage until V_{OD} turns to "H".

9.1.11 Charge Overcurrent Delay Time, Charge Overcurrent Release Delay Time (Test circuit 3)

Apply 3.6V to V1, and decrease V2 from 0V (Normal mode) to Charge **Overcurrent Detection Voltage (V_{CIP}), Charge Overcurrent Delay Time (T_{CIP})** is the time from V2 falls below **Charge Overcurrent detection voltage** until V_{OC} turns to "L".

Apply 3.6V to V1, and increase V2 from Charge Overcurrent Detection Voltage (V_{CIP}) to 0V. Charge Overcurrent release delay time (T_{CIPR}) is the time from V2 exceeds Charge overcurrent release voltage until V_{OC} turns to "H".

9.1.12 Short Circuit Delay Time, Short Circuit Release Delay Time (Test circuit 3)

Apply 3.2V to V1, and increase V2 from 0V (Normal mode) to **Short Circuit Detection Voltage** (V_{SIP}). Short Circuit Delay Time (T_{SIP}) is the time from V2 exceeds Short Circuit Detection Voltage until V_{OD} turns to "L".

Apply 3.2V to V1, and decrease V2 from 3.2V (Short Circuit mode) to 0V. Short Circuit Release Delay Time (T_{SIPR}) is the time from V2 falls below Short Circuit Release Voltage until V_{OD} turns to "H".

9.1.13 **OV battery charge starting charger voltage** (Test circuit 2)

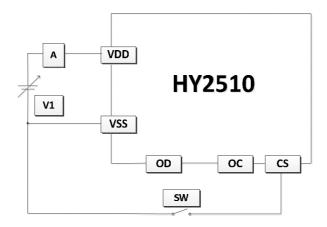
The 0V battery charge starting charger voltage (V_{0ch}) is defined as the voltage V1 at which V_{OC} turns to "H" ($V_{OC} = V_{SS}$) when the voltage V2 is gradually decreased from the setting condition of V1=0V, V2=-1.2V.

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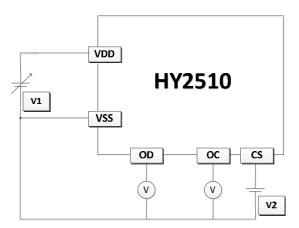
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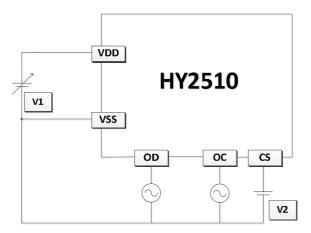
9.2. Test circuit



Test circuit 1



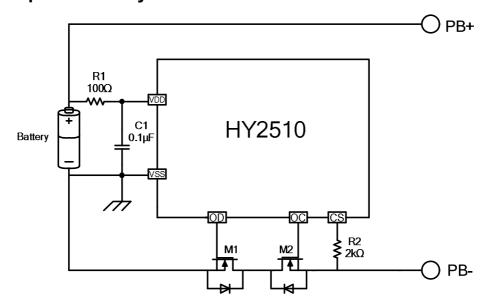
Test circuit 2



Test circuit 3



10. Example of Battery Protection IC Connection



Symbol	Device Name	Purpose	Min.	Тур.	Max.	Remark
R1	Resistor	limit current, stabilize VDD and strengthen ESD protection	100Ω	100Ω	470Ω	*1
R2	Resistor	limit current	1kΩ	2kΩ	2.2kΩ	*2
C1	Capacitor	stabilize VDD	0.01µF	0.1µF	1.0µF	*3
M1	N-MOSFET	Discharge control	-	-	-	*4
M2	N-MOSFET	Charge control	-	-	-	*5

- *1. R1 should be as small as possible to avoid lowering the overcharge detection accuracy due to current consumption. When a charger is connected in reversed, the current flows from the charger to the IC. At this time, if R1 is connected to high resistance, the voltage between VDD pin and VSS pin may exceed the absolute maximum rating.
- *2. If R2 has a resistance higher than $2.2k\Omega$, the charging current may not be cut when a high-voltage charger is connected. Please select as large a resistance as possible to prevent current when a charger is connected in reversed.
- *3. C1 will stabilize the supply voltage of VDD, the value of C1 should be equal to or more than 0.01µF.
- *4. If a FET with a threshold voltage equal to or higher than the overdischarge detection voltage is applied, discharging may be stopped before overdischarge is detected.
- *5. If the withstanding voltage between the gate and source is lower than the charger voltage, the FET may be destroyed.

Caution:

- 1. The above constants may be changed without notice, please download the most up-to-date datasheet on our website. http://www.hycontek.com
- 2. It is advised to perform thorough evaluation and test if peripheral devices need to be adjusted.



11. Description of Operation

11.1. Normal Status

The IC monitors the voltage of the battery connected between the VDD pin and VSS pin and the voltage difference between the CS pin and VSS pin to control charging and discharging.

When the battery voltage is in the range from overdischarge detection voltage (V_{DL}) to overcharge detection voltage (V_{CU}), and the CS pin voltage is in the range from the charge overcurrent detection voltage (V_{CIP}) to discharge overcurrent detection voltage (V_{DIP}), the IC turns both the charging and discharging control MOSFET on. Such status is referred to as the normal status, when in this status, charging and discharging can both be carried out freely.

Notice:

In case of discharge function may not be carried out when The IC connected battery, in this case, connecting a charger to reset and normal operating status is returned.

11.2. Overcharge Status

When the battery voltage is higher than the overcharge detection voltage (V_{CU}) during charging under the normal status and the sustaining time of such status is longer than the overcharge detection delay time (T_{OC}), The IC will turns the charging control MOSFET off (OC pin) to stop charging .This condition is called the overcharge status.

The overcharge status can be released by the following two cases:

Condition: disconnect charger

- (1)When the battery voltage is lowers than or equal to the overcharge release voltage (V_{CR}), the IC turns the charging MOSFET off and return to normal status.
- (2) When the load is connected, the discharge current will pass through parasitical diode of charging control MOSFET. At this time, CS pin will detect "Diode forward voltage drop (Vf)". When CS pin voltage rises higher than discharge overcurrent detection voltage (V_{DIP}) and battery voltage lowers than overcharge detection voltage (V_{CU}), the overcharge status will be released and return to normal status.

Caution:

When a charger is connected after overcharge detection, the overcharge status is not released even if the battery voltage is below overcharge release voltage (V_{CR}). The overcharge status is released when the CS pin voltage goes over the charge overcurrent detection voltage (V_{CIP}) by removing the charger.



11.3. Overdischarge Status

When the battery voltage falls below than the overdischarge detection voltage (V_{DL}) during discharging in the normal status and the sustaining time of such status is longer than the overdischarge detection delay time (T_{OD}), The IC will turns the discharging control MOSFET off (OD pin). This status is called the overdischarge status.

The overdischarge status will be released by three cases:

- (1) When CS pin voltage is equal to or lower than the charge overcurrent detection voltage (V_{CIP}) by charging and the VDD pin voltage is higher than the overdischarge detection voltage (V_{DL}).
- (2) When CS pin voltage is equal to or higher than the charge overcurrent detection voltage (V_{CIP}) and the VDD pin voltage is higher than the overdischarge release voltage (V_{DR}).
- (3) Without connecting a charger, if the VDD pin voltage is higher than overdischarge release voltage (V_{DR}), the overdischarge status will be released. Such function is referred to as Auto Overdischarge Recovery.

11.4. Discharge Overcurrent Status (Discharge Overcurrent & Short Circuit)

Under normal condition, The IC continuously monitors the discharge current by sensing the voltage of CS pin. If the voltage of CS pin exceeds the overcurrent detection voltage (V_{DIP}) and the sustaining time of such status is longer than the overcurrent delay time (T_{DIP}), the output voltage on OD pin of IC becomes low level from high level, such that the MOSFET for discharging control is switched off, This status is called the discharge overcurrent status.

If the voltage of CS pin exceeds the short circuit detection voltage (V_{SIP}) and the sustaining time of such status is longer than the short circuit delay time (T_{SIP}), the output voltage on OD pin of IC becomes low level from high level, such that the MOSFET for discharging control is switched off. This condition is called the short circuit status.

When the impedance between PB+ and PB- is higher than discharge overcurrent and short circuit release impedance ($25k\Omega$ typ.), the discharge overcurrent status and short circuit status will be released and return to normal operation status. In addition, if the impedance between PB+ and PB- is less than discharge overcurrent and short circuit release impedance, CS pin voltage will lower than overcurrent detection voltage (V_{DIP}) after the charger is connected, discharge overcurrent status and short circuit status will be released and return to normal operation status.

Caution:

(1) If the charger is connected and polarity direction is in reversed, the current direction is the same as discharge current in the circuit. If CS pin voltage goes higher than overcurrent detection voltage (V_{DIP}), it will enter into discharge overcurrent protection status to block out in-circuit current.



11.5. Charge Overcurrent Status

When a battery is in the normal status, the voltage of the CS pin is lower than the charge overcurrent detection voltage (V_{CIP}) and the sustaining time of such status is longer than the charge overcurrent detection delay time (T_{CIP}), The IC will turns the charging control MOSFET off (OC pin) to stop charging. This status is called the charge overcurrent status.

This IC will be restored to the normal status from the charge overcurrent status when the voltage at the CS pin returns to charge overcurrent detection voltage (V_{CIP}) or higher by removing the charger.

11.6.0V Battery Charging Function "Available"

This function is used to recharge a connected battery which voltage is 0V due to self-discharge. When the 0V battery charge starting charger voltage (V_{0ch}) or a higher voltage is applied between the battery+ (PB+) and battery- (PB-) pins by connecting a charger, the charging control MOSFET gate is fixed to the VDD pin voltage.

When the voltage between the gate and the source of the charging control MOSFET becomes equal to or higher than the turn on voltage due to the charger voltage, the charging control MOSFET is turned on to initiate charging. At this time, the discharging control MOSFET is off and the charging current flows through the internal parasitic diode in the discharging control MOSFET. When the battery voltage becomes equal to or higher than overdischarge detection voltage (V_{DL}), The IC will enter into the normal status.

Caution

Some battery provides do not recommend charging for a completely self-discharged battery. Please ask the battery provider to determine whether to enable or prohibit the 0V battery charging function.

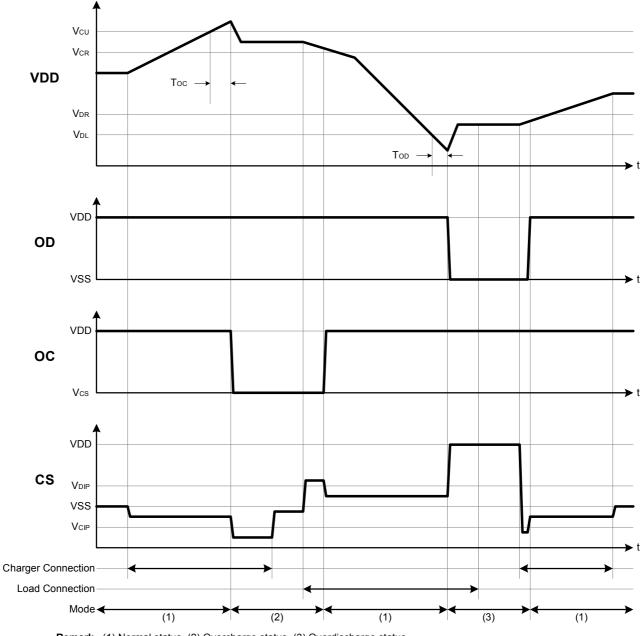
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12. Timing Chart

12.1 Overcharge Detection, Overdischarge Detection



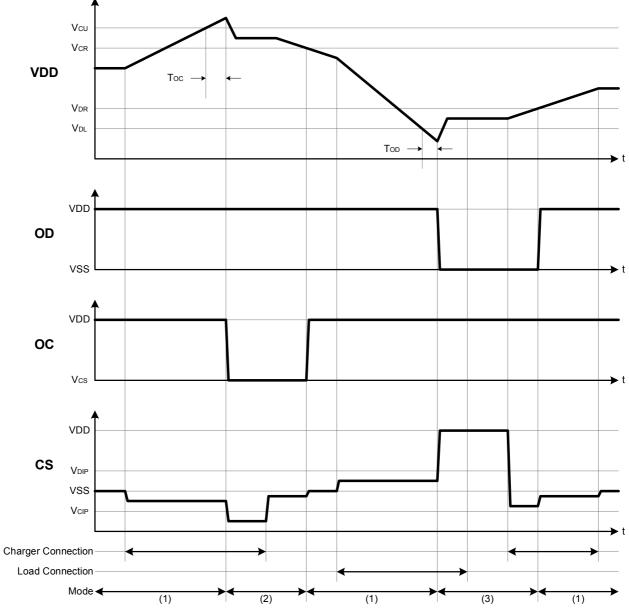
Remark (1) Normal status, (2) Overcharge status, (3) Overdischarge status

Remark:

- (a) Overcharge release condition: $V_{CS} > V_{DIP} \& V_{DD} < V_{CU}$.
- (b) Overdischarge release condition: V_{CS}<V_{CIP} & V_{DD}>V_{DL}.



12.2 Overcharge Detection, Overdischarge Detection



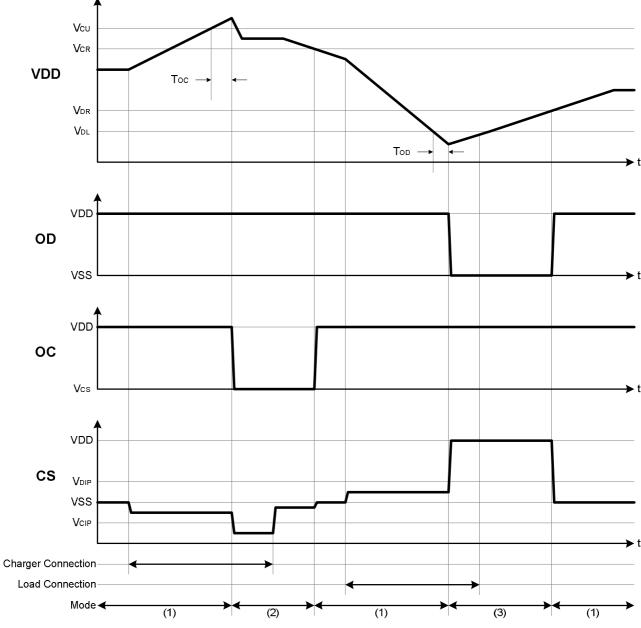
Remark (1) Normal status, (2) Overcharge status, (3) Overdischarge status

Remark:

- (a) Overcharge release condition: $V_{\text{CIP}} \!\!<\!\! V_{\text{CS}} \!\!<\!\! V_{\text{DIP}}$ & $V_{\text{DD}} \!\!<\!\! V_{\text{CR}}.$
- (b) Overdischarge release condition: V_{CS} > V_{CIP} & V_{DD} > V_{DR} .



12.3 Overcharge Detection, Overdischarge Detection (with auto overdischarge recovery function)



Remark (1) Normal status, (2) Overcharge status, (3) Overdischarge status

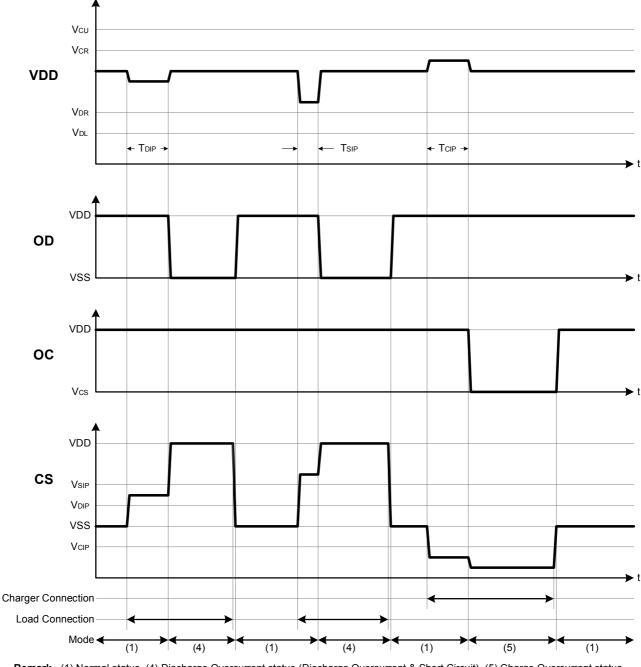
Remark:

(a) overcharge release condition: $V_{CIP} < V_{CS} < V_{DIP} \& V_{DD} < V_{CR}$.

(b) overdischarge release condition: $V_{DD} > V_{DR}$.



12.4 Discharge overcurrent Detection, Short circuit Detection, Charge Overcurrent Detection

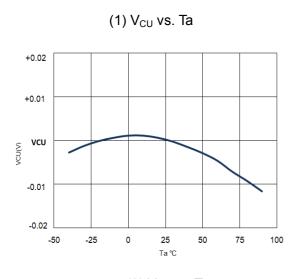


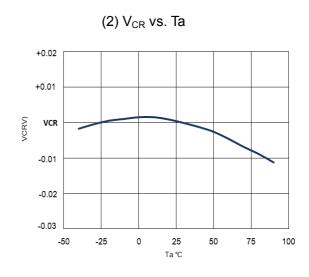
Remark (1) Normal status, (4) Discharge Overcurrent status (Discharge Overcurrent & Short Circuit), (5) Charge Overcurrent status

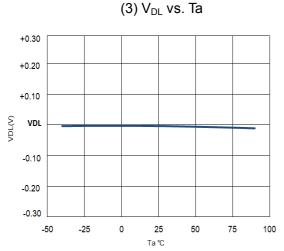


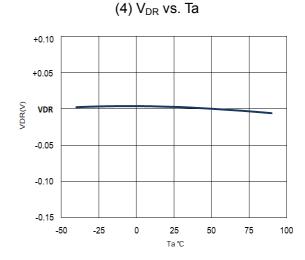
13. Characteristics (Typical Value)

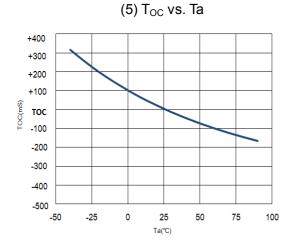
Overcharge Detection/Release Voltage, Overdischarge Detection/Release Voltage/Discharge Overcurrent Detection Voltage, Short Circuit Detection Voltage, Charge Overcurrent Detection Voltage and Delay Time.

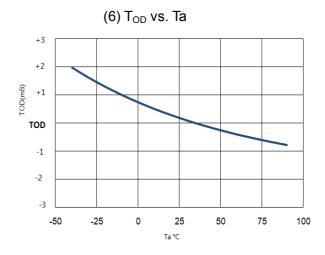




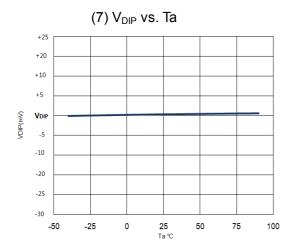


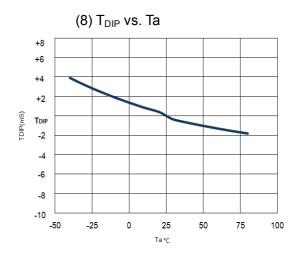


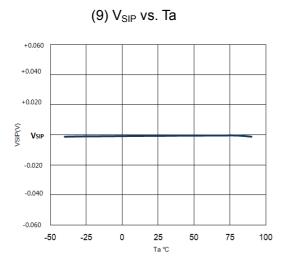


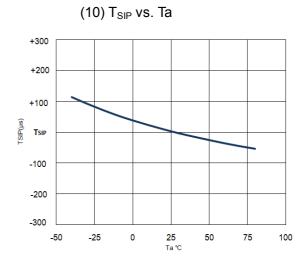


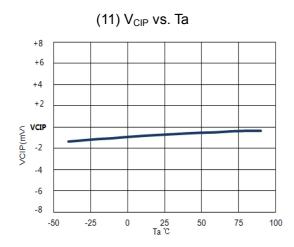


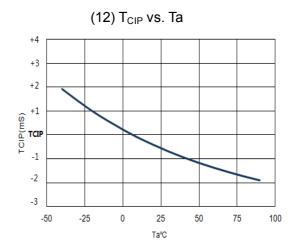




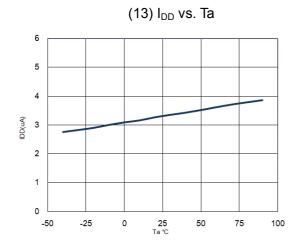


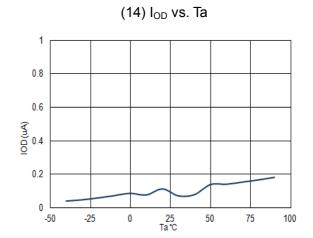










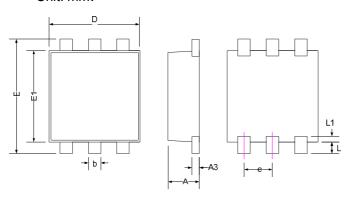


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14. Package Information and Land Pattern Design Recommendations 14.1.SON-1.6*1.6-6L Outline

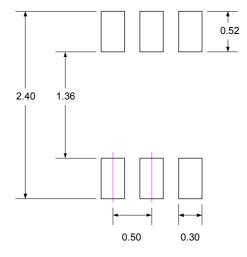
Unit: mm.



SYMBOLS	MIN	MAX				
Α	0.50	0.55	0.60			
А3	0.08	0.13	0.18			
b	0.17	0.22	0.27			
D	1.55	1.60	1.65			
E1	1.55	1.60	1.65			
E	1.90	2.00	2.10			
L	0.10	0.20	0.30			
L1	0.10 REF					
е	0.50 BASIC					

Note: Do not include Mold Flash or Protrusions.

14.2. Land Pattern Design Recommendations



Note:

- 1. Publication IPC-7351 is recommended for alternate designs.
- 2. Unit: mm.
- 3. http://www.hycontek.com/attachments/MSP/OJTI-HM-2013-002.pdf.

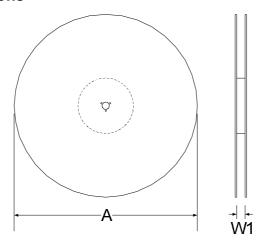


15. Tape & Reel Information

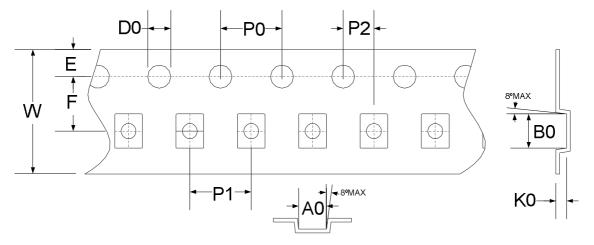
15.1. Tape & Reel Information---SON-1.6*1.6-6L

Unit: mm

15.1.1. Reel Dimensions



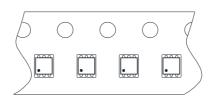
15.1.2. Carrier Tape Dimensions



SYMBOLS		eel nsions				Carr	ier Tap	e Dimer	sions			
	Α	W1	A0	В0	K0	P0	P1	P2	Е	F	D0	W
Spec.	178	9.4	1.80	2.20	0.70	4.00	4.00	2.00	1.75	3.50	1.50	8.00
Tolerance	±2.00	±1.50	±0.05	±0.05	±0.10	±0.10	±0.10	±0.05	±0.10	±0.05	±0.10	±0.20

Note: 10 Sprocket hole pitch cumulative tolerance is ±0.20mm.

15.1.3. PIN1 direction





16. Revision Record

Major differences are stated thereinafter:

Revision Summary Version Page

V01 First Edition